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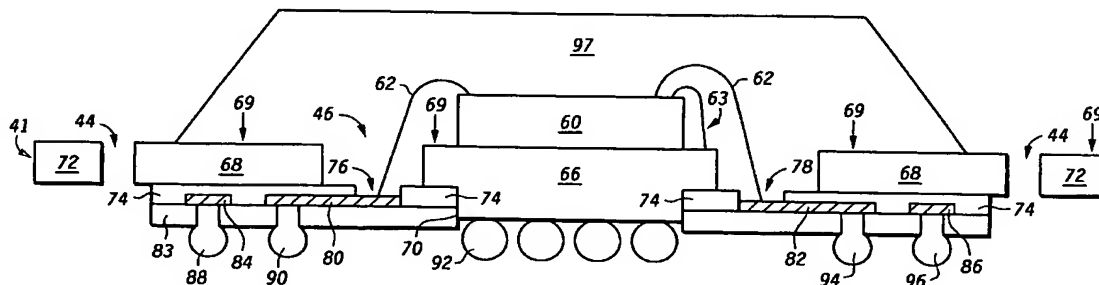
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(54) Title: A PACKAGED INTEGRATED CIRCUIT HAVING A HEAT SPREADER AND METHOD THEREFOR



(57) Abstract: An integrated circuit (60) is packaged, in one embodiment, by wire bonding to pads (76, 78) supported by tape (83). The tape (83) also supports traces (80, 82) that run from the wire bonded location (76) to a pad for solder balls (90, 94). A heat spreader (69) is thermally connected to the integrated circuit (60) and is located not just in the area under the die (60) but also extends to the edge of the package in the area outside the wire bonding location. This outer area (68) is thermally connected to the area (66) under the die (60) by thermal bars (66) that run between some of the wire bond locations (76, 78). During the manufacturing of the package the heat spreader (69) is connected to slotted rails by tie bars (48, 50, 52, 54). During singulation, the tie bars (48, 50, 52, 54) are easily broken or sawed because they are significantly reduced in thickness from the thickness of the heat spreader (66) as a whole.

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